

## 1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

<b>Part Number :</b>	CJM5R7SN03B
<b>Package Type :</b>	DFNWB2x2-6L

## 2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Si	7440-21-3	100%	4.33%
Lead Frame	Copper (Cu)	7440-50-8	97.3925%	18.80%
	Iron (Fe)	7439-89-6	2.3500%	
	Phosphorus (P)	7723-14-0	0.0825%	
	Zinc (Zn)	7440-66-6	0.1250%	
	Lead (Pb)	7439-92-1	0.0050%	
	Silver (Ag)	7440-22-4	0.0450%	
Epoxy	Lead (Pb)	7439-92-1	92.5000%	16.86%
	Tin(Sn)	7440-31-5	5.0000%	
	Silver (Ag)	7440-22-4	2.5000%	
Wire	Aurum(Au)	7440-57-5	99.9900%	0.30%
	Others	/	0.0100%	
Mold Compound	Epoxy resin A	Trade Secret	3.0000%	58.46%
	Epoxy resin B	Trade Secret	3.0000%	
	Phenol Resin A	Trade Secret	3.0000%	
	Phenol Resin B	Trade Secret	3.0000%	
	Silica(Amorphous) A	60676-86-0	76.9500%	
	Silica(Amorphous) B	7631-86-9	7.5000%	
	Metal Hydroxide	Trade Secret	3.0000%	
	Carbon black	1333-86-4	0.5500%	
Plating	Tin(Sn)	7440-31-5	99.9900%	1.26%
	Others	/	0.0100%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.